

POWER MOS FET FIELD EFFECT POWER TRANSISTOR

IRFD212,213

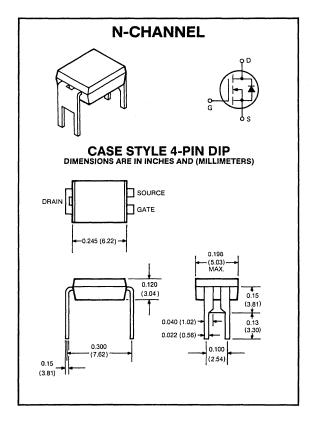
0.45 AMPERES 200, 150 VOLTS RDS(ON) = 2.4 Ω

This series of N-Channel Enhancement-mode Power MOSFETs utilizes GE's advanced Power DMOS technology to achieve low on-resistance with excellent device ruggedness and reliability.

This design has been optimized to give superior performance in most switching applications including: switching power supplies, inverters, converters and solenoid/relay drivers. Also, the extended safe operating area with good linear transfer characteristics makes it well suited for many linear applications such as audio amplifiers and servo motors.

Features

- Polysilicon gate Improved stability and reliability
- No secondary breakdown Excellent ruggedness
- Ultra-fast switching Independent of temperature
- Voltage controlled High transconductance
- Low input capacitance Reduced drive requirement
- Excellent thermal stability Ease of paralleling



maximum ratings (T_A = 25°C) (unless otherwise specified)

RATING	SYMBOL	IRFD212	IRFD213	UNITS
Drain-Source Voltage	V _{DSS}	200	150	Volts
Drain-Gate Voltage, R_{GS} = 1M Ω	V _{DGR}	200	150	Volts
Continuous Drain Çurrent @ $T_A = 25^{\circ} C^{(1)}$ @ $T_A = 100^{\circ} C^{(1)}$	σا	0.45 0.30	0.45 0.30	A A
Pulsed Drain Current ⁽²⁾	I _{DM}	1.8	1.8	Α
Gate-Source Voltage	V _{GS}	±20	±20	Volts
Total Power Dissipation @ T _A = 25°C Derate Above 25°C	P _D	1.0 8	1.0 8	Watts mW/°C
Operating and Storage Junction Temperature Range	T _J , T _{STG}	-55 to 150	-55 to 150	°C

thermal characteristics

Thermal Resistance, Junction to Ambient ⁽¹⁾	$R_{ heta JA}$	125	125	°C/W
Maximum Lead Temperature for Soldering Purposes: 1/8" from Case for 5 Seconds	TL	300	300	°C

⁽¹⁾ Device mounted to vertical pc board in free air with drain lead soldered to 0.20 in² minimum copper run area.

(2) Repetitive Rating: Pulse width limited by max. junction temperature.

electrical characteristics ($T_A = 25^{\circ}C$) (unless otherwise specified)

CHARACTERISTIC		SYMBOL	MIN	TYP	MAX	UNIT
off characteristics						
Drain-Source Breakdown Voltage (V _{GS} = 0V, I _D = 250 μA)	IRFD212 IRFD213	BVDSS	200 150	_	_	Volts
Zero Gate Voltage Drain Current (V _{DS} = Max Rating, V _{GS} = 0V, T _A = 25°C) (V _{DS} = Max Rating, × 0.8, V _{GS} = 0V, T _A = 125°C)		IDSS		_	250 1000	μΑ
Gate-Source Leakage Current ($V_{GS} = \pm 20V$)		I _{GSS}	_	_	±500	nA

on characteristics*

Gate Threshold Voltage $(V_{DS} = V_{GS}, I_D = 250 \mu A)$	T _A = 25°C	V _{GS(TH)}	2.0	_	4.0	Volts
On-State Drain Current (V _{GS} = 10V, V _{DS} = 10V)		I _{D(ON)}	0.45			Α
Static Drain-Source On-State Resistance (V _{GS} = 10V, I _D = 0.3A)		R _{DS(ON)}		1.6	2.4	Ohms
Forward Transconductance (V _{DS} = 10V, I _D = 0.3A)		9fs	0.35	0.4	_	mhos

dynamic characteristics

Input Capacitance	V _{GS} = 0V	C _{iss}	_	120	150	pF
Output Capacitance	V _{DS} = 25V	Coss	_	40	80	pF
Reverse Transfer Capacitance	f = 1 MHz	C _{rss}	_	10	25	pF

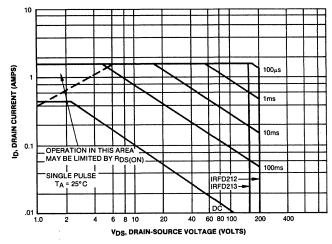
switching characteristics*

Turn-on Delay Time	V _{DS} = 90V	t _{d(on)}	_	5		ns
Rise Time	I _D = 0.3A, V _{GS} = 15V	t _r	_	15	_	ns
Turn-off Delay Time	$R_{GEN} = 50\Omega$, $R_{GS} = 12.5\Omega$	^t d(off)	_	10	_	ns
Fall Time	$R_{GS (EQUIV.)} = 10\Omega$	t _f		10	_	ns

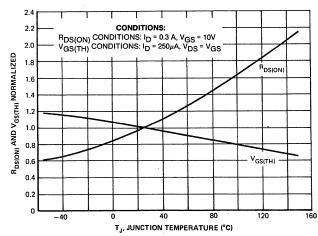
source-drain diode ratings and characteristics*

Continuous Source Current		Is		_	0.45	Α
Pulsed Source Current		I _{SM}			1.8	Α
Diode Forward Voltage (T _A = 25°C, V _{GS} = 0V)	_S = 0.45A	V _{SD}	_	0.7	1.8	Volts
Reverse Recovery Time (I _S = 0.6A, di _s /dt = 100A/ μ s, T _A = 125°C)		t _{rr} Q _{RR}	_	100 0.75		ns μC

^{*}Pulse Test: Pulse width \leq 300 μ s, duty cycle \leq 2%



MAXIMUM SAFE OPERATING AREA



TYPICAL NORMALIZED $\mathbf{R}_{\text{DSION}}$ AND $\mathbf{V}_{\text{GS|TH|}}$ VS. TEMP.